

Image



Docket No.: M4065.0018/P018-A
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Rodney C. Langley, et al.

Confirmation No.: 2423

Application No.: 09/507,465

Group Art Unit: 1765

Filed: February 22, 2000

Examiner: M. Anderson

For: METHOD AND APPARATUS FOR
PLASMA ETCHING A WAFER

RESPONSE TO NON-COMPLIANT AMENDMENT UNDER 37 CFR 1.121

MS Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Notice of Non-Compliant Amendment dated February 20, 2004, please reconsider the above-identified U.S. patent application in view of the Amendment submitted October 7, 2003 and the following remarks:

A full listing of claims begins on page 2 of this paper.

Remarks begin on page 6 of this paper.